

## **Technical Data Sheet**

MODEL NO: S5730ANG4P

**5730 Package 5.7\*3.0mm Top LEDs** 

### Features:

• Compatible with automatic placement equipment

• Compatible with reflow solder process

## Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN	Green	Water Clear

## Electrical/Optical Characteristics(Ta=25 $^{\circ}$ C)

Parameter	Test	Symbol	Value			Linit
	Condition		Min	Тур	Max	Unit
Dominant wavelength	I <sub>F</sub> =150mA	λО	515	520	525	nm
Forward voltage	I <sub>F</sub> =150mA	VF	3.0		3.4	V
Luminous Flux	I <sub>F</sub> =150mA	ф (lm)	20	25		lm
Luminous intensity	I <sub>F</sub> =150mA	lv		6000	7000	mcd
Viewing angle at 50% lv	I <sub>F</sub> =150mA	2 <del>0</del> 1/2		120		Deg
Reverse current	V <sub>R</sub> =5V	lr			10	μА

## Absolute Maximum Ratings(Ta= $25^{\circ}$ C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	500	mW
Forward current	lF	150	mA
Reverse voltage	VR	5	V
Operating temperature range	Тор	-20 ~+80	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+80	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/10 duty f=1kHz)	IFP	500	mA

13APR25B

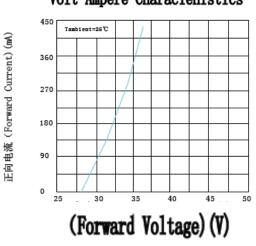
# PACKAGING DIMENSIONS (mm):



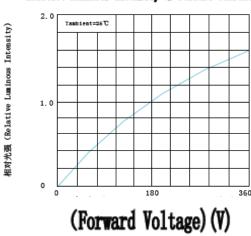


# (Optical-Electrical Characteristic)

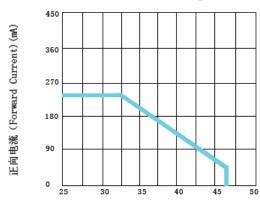
Volt-Ampere Characienistics



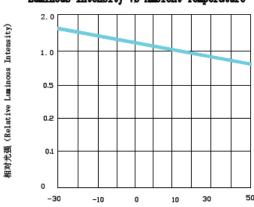
Relative Luminous Intensity VS Forward Current



Forward Current Derating Curve

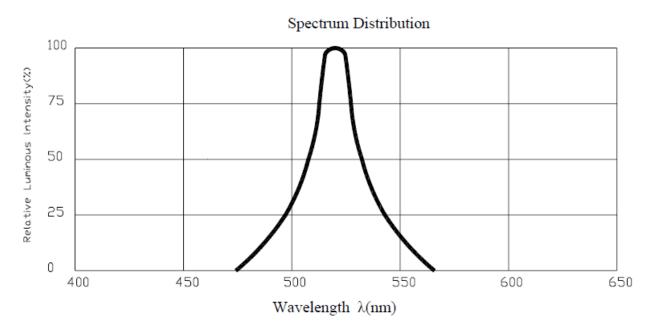


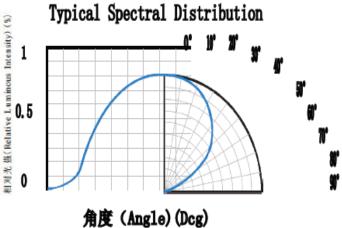
Luminous Intensity VS Ambient Temperature



(Ambient Temperature) (°C)

(Ambient Temperature) (°C)





## **Precautions For Use:**

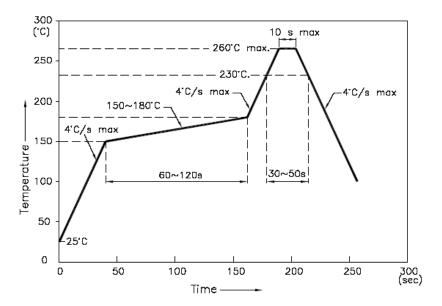
### Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

### **Storage**

- 1. The operation of temperature and R.H. are :  $5^{\circ}$ C  $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}\text{C}\pm5^{\circ}\text{C}$  for 15hrs.

## ■ Reflow Temp/Time



### NOTES:

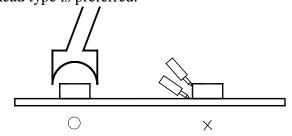
- 1. We recommend the reflow temperature  $245^{\circ}\text{C}(\pm 5^{\circ}\text{C})$ .the maximum soldering temperature should be limited to  $260^{\circ}\text{C}$ .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

### **■**Soldering iron

Basic spec is  $\leq$  5sec when 260°C. If temperature is higher, time should be shorter (+10°C  $\rightarrow$  -1sec ). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

### **■**Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \ solder etc.